Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	59089	("v" near10 groove)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/24 18:04
L3	7154	L2 and etch$3	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/24 18:04
L4	5537	L3 and (die wafer dice substrate)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/24 18:04
L5	4115	L4 and (thin$3 polish$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/24 18:05
L6	1661	L5 and (IC (integrat$3 near5 circuit))	US-PGPUB; USPAT; USOCR	OR	ON	2005/06/24 18:03
L7	20960	("v" near10 groove)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 18:04
L9	1553	L7 and etch$3	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 18:04
L10	1270	L9 and (die wafer dice substrate)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 18:05
L11	221	L10 and (thin$3 polish$3)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/24 18:05